*MPEC REPORT 10*

**PCB Soldering and Copper Clad Etching**

WEEKLY PROGRESS:

**PCB Soldering:**

In this week, we soldered the PCB completely.

Problems faced:

1. We didn’t have our wire cutter with us, so we borrowed it form a different group.
2. We still didn’t have three of the components in the circuit, so, we soldered everything except for them.

**Copper Clad Etching:**

In this week, we completed half of the process of etching on the copper clad. We first took the printout of the gerber file on a photo paper, cleaned the copper clad with isopropyl solution, then we stuck the printout on the copper clad, and ironed it. The heat caused the ink on the photo paper to stick to the copper clad.

Problems faced:

1. Not all of the ink was transferred onto the copper clad so we had to trace and draw the circuit with the help of a permanent marker. We also made the lines a bit thicker so that the ink doesn’t disappear mid-process.

The end result was:

